

# John Smith

Hatboro, PA - Email me on Indeed: [indeed.com/r/John-Smith/bf22f42ce8ce934a](https://www.indeed.com/r/John-Smith/bf22f42ce8ce934a)

Willing to relocate

Authorized to work in the US for any employer

## WORK EXPERIENCE

### **Inventor, Software Architect, Designer and Developer**

99eggs, Inc - Hatboro, PA - April 2014 to Present

I launched this company as an Internet technology development company, with the intention of developing several ideas I had been accumulating over time. I have produced several proof-of-concept projects, plus a more complete, beta-test level system for Internet-based multi-track music recording to enable crowd-sourcing music production.

Unfortunately, I have not yet turned my technical achievements into a successful business, but fortunately my costs are low enough and development is far enough along that I can keep it going with very little additional time or money, and am seeking employment.

I plan to use the site as a portfolio of not just my approach to software development and adaptability to new challenges, but of skills and talents not demonstrated by other previous employment, especially in the area of visual design.

#### **R&D:**

Research on 3D photography, digital 3D cameras, and 3D viewing devices/techniques.

#### **Devices:**

Invention 1: Created an inexpensive stereoscope for use with tablet computers

Invention 2: Created a stereoscopic attachment to act as a 3D viewer for creating inexpensive do-it-yourself 3D video cameras from 2 digital cameras.

#### **Web Application:**

Online Music Workshop: Designed/Developed a multi-track, multi-media, multi-device, online music crowd-sourcing system. A functional test version is available for use at:

<http://www.99eggs.com/OMW/omwstart.php>

### **Software Engineer and Development Team Lead**

Kulicke & Soffa Industries Inc - Fort Washington, PA - October 1999 to November 2013

System software engineer for the development of 5 product lines: Triton wedge/ribbon bonder, ATX2 ballbonder, Ultra/Elite ballbonder, ATX3 ballbonder, and The Premier bump bonder (wedge bonders, ballbonders, and bump bonders are high-precision industrial robots used in the manufacturing of semiconductors)

#### **Areas of Responsibility:**

Software Requirements/Design: Synthesized requests, requirements, and specifications from mechanical, electrical, and process engineering, the subsystem software specialists, and marketing/sales representatives, to develop system software requirements and specifications.

Development (Specific Areas of Design/Development): System initialization, data storage, calibrations, system configuration, power control

Development Team Lead: Led development teams with members in the US, Singapore, China, and India. Responsibilities included creating design specifications, assigning, training, and managing.

System Integration: Working in the lab with the hardware, software, and process engineers to integrate new features and components, I was responsible for identifying and determining requirements for any additional features and modifications identified during system and process testing.

Product definition/configuration: With product lines supporting many different mechanical and electrical options, I was responsible for features that properly configure machines ensuring only the correct software and parameters are used. With these machines, wrong parameters or code can cause damage to the machine or the customer's materials, or even injuries.

Misc. Accomplishments:

Various cost-saving features created through the creative alternate uses of existing system components and subsystems. One example: an alternate system installation and data collection/storage scheme that allowed for the removal of an expensive high capacity hard drive.

Recognized for my ability to solve hard-to-diagnose problems that result from interactions within systems, such as low-frequency timing problems.

## EDUCATION

### **BS in Mathematics**

DeSales University

## LINKS

<http://www.99eggs.com>

<http://www.99eggs.com/OMW/omwstart.php>

## PATENTS

### **Calibration Apparatus For Bondhead of Wire Bonding Machine (#US 7,624,904 B1)**

December 2009

The device is a calibration gauge for the pivot bondhead of the K&S ballbonders. The gauge enables the use of the bondhead camera to detect the point of perpendicularity, which is the optimal position for wire bonding.

## ADDITIONAL INFORMATION

Additional Areas of Expertise:

Extensive experience in all aspects of digital audio and video production and processing

Experience with digital 3D photography/video production and processing

Areas of Personal Study/Interest:

Considerable study and analysis of Virtual Reality concepts, and the state of the art in VR hardware and methodologies

Lifelong personal/professional study of the engineering of Artificial Intelligence.